

74AHC14; 74AHCT14

Hex inverting Schmitt trigger

Rev. 04 — 25 April 2008

Product data sheet

1. General description

The 74AHC14; 74AHCT14 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7A.

The 74AHC14; 74AHCT14 provides six inverting buffers with Schmitt-trigger action. They are capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

2. Features

- Balanced propagation delays
- All inputs have Schmitt-trigger actions
- Inputs accept voltages higher than V_{CC}
- Input levels:
 - ◆ For 74AHC14: CMOS level
 - ◆ For 74AHCT14: TTL level
- ESD protection:
 - ◆ HBM EIA/JESD22-A114E exceeds 2000 V
 - ◆ MM EIA/JESD22-A115-A exceeds 200 V
 - ◆ CDM EIA/JESD22-C101C exceeds 1000 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74AHC14				
74AHC14D	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74AHC14PW	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74AHC14BQ	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1
74AHCT14				
74AHCT14D	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74AHCT14PW	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74AHCT14BQ	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

4. Functional diagram

mna204

Fig 1. Logic symbol

001aac497

Fig 2. IEC logic symbol

mna025

Fig 3. Logic diagram (one Schmitt-trigger)

5. Pinning information

5.1 Pinning

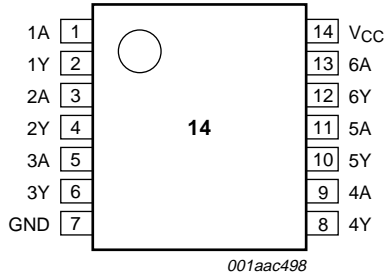
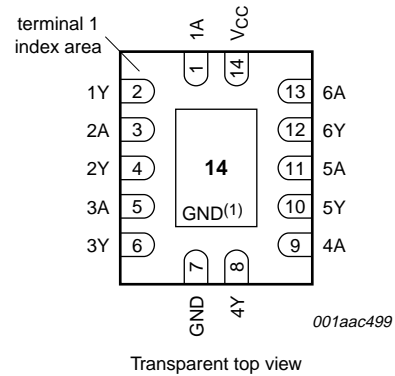


Fig 4. Pin configuration SO14 and TSSOP14



- (1) The die substrate is attached to this pad using conductive die attach material. It can not be used as a supply pin or input.

Fig 5. Pin configuration DHVQFN14

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A	1	data input 1
1Y	2	data output 1
2A	3	data input 2
2Y	4	data output 2
3A	5	data input 3
3Y	6	data output 3
GND	7	ground (0 V)
4Y	8	data output 4
4A	9	data input 4
5Y	10	data output 5
5A	11	data input 5
6Y	12	data output 6
6A	13	data input 6
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function table^[1]

Input	Output
nA	nY
L	H
H	L

[1] H = HIGH voltage level;
L = LOW voltage level.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
V_I	input voltage		-0.5	+7.0	V
I_{IK}	input clamping current	$V_I < -0.5$ V	[1] -20	-	mA
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1] -20	+20	mA
I_O	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5)$ V	-25	+25	mA
I_{CC}	supply current		-	+75	mA
I_{GND}	ground current		-75	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[2] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 packages: above 70 °C the value of P_{tot} derates linearly at 8 mW/K.
For TSSOP14 packages: above 60 °C the value of P_{tot} derates linearly at 5.5 mW/K.
For DHVQFN14 packages: above 60 °C the value of P_{tot} derates linearly at 4.5 mW/K.

8. Recommended operating conditions

Table 5. Operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
74AHC14						
V_{CC}	supply voltage		2.0	5.0	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	°C
74AHCT14						
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	°C

9. Static characteristics

Table 6. Static characteristics
At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74AHC14										
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = -50 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = -50 μA; V _{CC} = 3.0 V	2.9	3.0	-	2.9	-	2.9	-	V
		I _O = -50 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -4.0 mA; V _{CC} = 3.0 V	2.58	-	-	2.48	-	2.40	-	V
		I _O = -8.0 mA; V _{CC} = 4.5 V	3.94	-	-	3.80	-	3.70	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 50 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 50 μA; V _{CC} = 3.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 50 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 3.0 V	-	-	0.36	-	0.44	-	0.55	V
		I _O = 8.0 mA; V _{CC} = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	2.0	-	20	-	40	μA
C _I	input capacitance		-	3	10	-	10	-	10	pF
C _O	output capacitance		-	4	-	-	-	-	-	pF
74AHCT14										
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = -50 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -8.0 mA; V _{CC} = 4.5 V	3.94	-	-	3.80	-	3.70	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 50 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 8.0 mA; V _{CC} = 4.5 V	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	2.0	-	20	-	40	μA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} - 2.1 V; other pins at V _{CC} or GND; I _O = 0 A; V _{CC} = 4.5 V to 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C _I	input capacitance		-	3	10	-	10	-	10	pF
C _O	output capacitance		-	4	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see Figure 7.

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit	
			Min	Typ ^[1]	Max	Min	Max	Min	Max		
74AHC14											
t _{pd}	propagation delay	nA to nY; see Figure 6 ^[2]									
		V _{CC} = 3.0 V to 3.6 V									
		C _L = 15 pF	-	4.3	12.8	1.0	15.0	1.0	16.0	ns	
		C _L = 50 pF	-	5.8	16.3	1.0	18.0	1.0	20.5	ns	
		V _{CC} = 4.5 V to 5.5 V									
		C _L = 15 pF	-	3.2	8.6	1.0	10.0	1.0	11.0	ns	
		C _L = 50 pF	-	4.2	10.6	1.0	12.0	1.0	13.5	ns	
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _I = GND to V _{CC} ^[3]	-	10	-	-	-	-	-	pF	
74AHCT14											
t _{pd}	propagation delay	nA to nY; see Figure 6 ^[2]									
		V _{CC} = 4.5 V to 5.5 V									
		C _L = 15 pF	-	4.0	7.0	1.0	8.0	1.0	9.0	ns	
		C _L = 50 pF	-	5.4	8.0	1.0	9.0	1.0	10.0	ns	
C _{PD}	power dissipation capacitance	f _i = 1 MHz; V _I = GND to V _{CC} ^[3]	-	12	-	-	-	-	-	pF	

[1] Typical values are measured at nominal supply voltage (V_{CC} = 3.3 V and V_{CC} = 5.0 V).

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

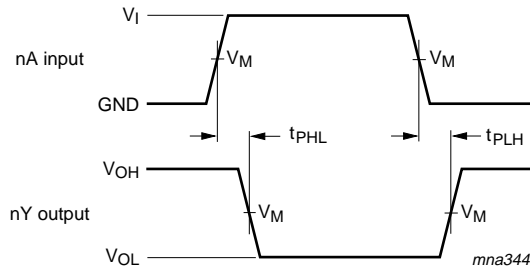
C_L = output load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

Σ(C_L × V_{CC}² × f_o) = sum of the outputs.

11. Waveforms

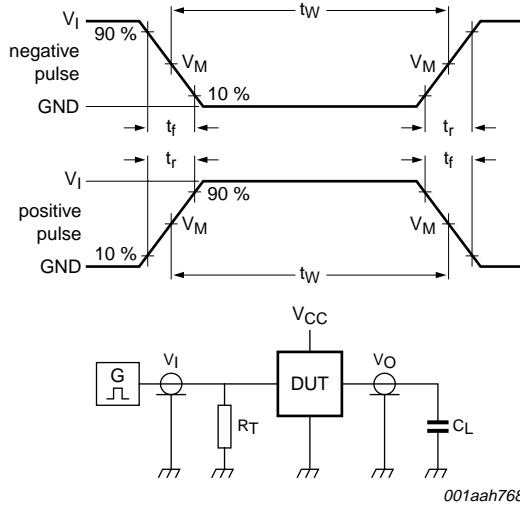


Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Input to output propagation delays

Table 8. Measurement points

Type	Input	Output
	V_M	V_M
74AHC14	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74AHCT14	1.5 V	$0.5 \times V_{CC}$



Test data is given in [Table 9](#).
 Definitions test circuit:
 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator
 C_L = Load capacitance including jig and probe capacitance

Fig 7. Load circuitry for measuring switching times

Table 9. Test data

Type	Input		Load	Test
	V_I	t_r, t_f	C_L	
74AHC14	V_{CC}	≤ 3.0 ns	50 pF, 15 pF	t_{PLH}, t_{PHL}
74AHCT14	3.0 V	≤ 3.0 ns	50 pF, 15 pF	t_{PLH}, t_{PHL}

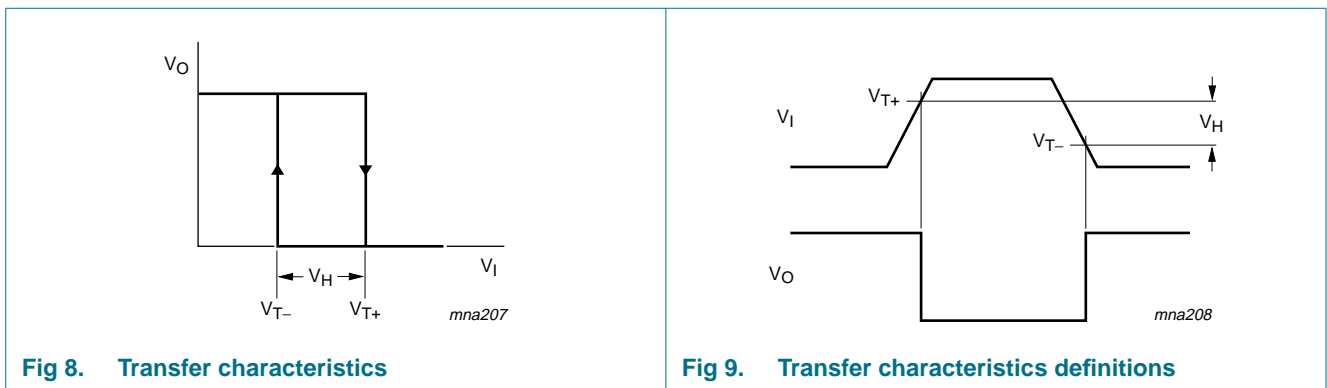
12. Transfer characteristics

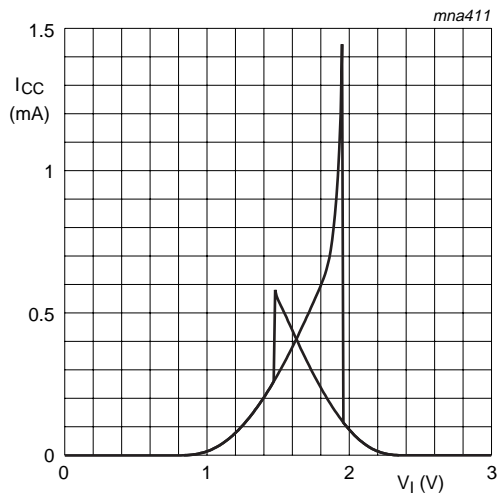
Table 10. Transfer characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); see Figure 8 and Figure 9.

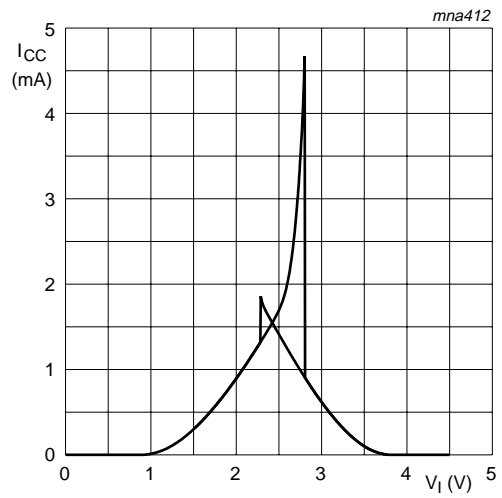
Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74AHC14										
V_{T+}	positive-going threshold voltage	$V_{CC} = 3.0$ V	-	-	2.2	-	2.2	-	2.2	V
		$V_{CC} = 4.5$ V	-	-	3.15	-	3.15	-	3.15	V
		$V_{CC} = 5.5$ V	-	-	3.85	-	3.85	-	3.85	V
V_{T-}	negative-going threshold voltage	$V_{CC} = 3.0$ V	0.9	-	-	0.9	-	0.9	-	V
		$V_{CC} = 4.5$ V	1.35	-	-	1.35	-	1.35	-	V
		$V_{CC} = 5.5$ V	1.65	-	-	1.65	-	1.65	-	V
V_H	hysteresis voltage	$V_{CC} = 3.0$ V	0.3	-	1.2	0.3	1.2	0.25	1.2	V
		$V_{CC} = 4.5$ V	0.4	-	1.4	0.4	1.4	0.35	1.4	V
		$V_{CC} = 5.5$ V	0.5	-	1.6	0.5	1.6	0.45	1.6	V
74AHCT14										
V_{T+}	positive-going threshold voltage	$V_{CC} = 4.5$ V	-	-	1.9	-	1.9	-	1.9	V
		$V_{CC} = 5.5$ V	-	-	2.1	-	2.1	-	2.1	V
V_{T-}	negative-going threshold voltage	$V_{CC} = 4.5$ V	0.5	-	-	0.5	-	0.5	-	V
		$V_{CC} = 5.5$ V	0.6	-	-	0.6	-	0.6	-	V
V_H	hysteresis voltage	$V_{CC} = 4.5$ V	0.4	-	1.4	0.4	1.4	0.35	1.4	V
		$V_{CC} = 5.5$ V	0.4	-	1.5	0.4	1.5	0.35	1.5	V

13. Transfer characteristics waveforms

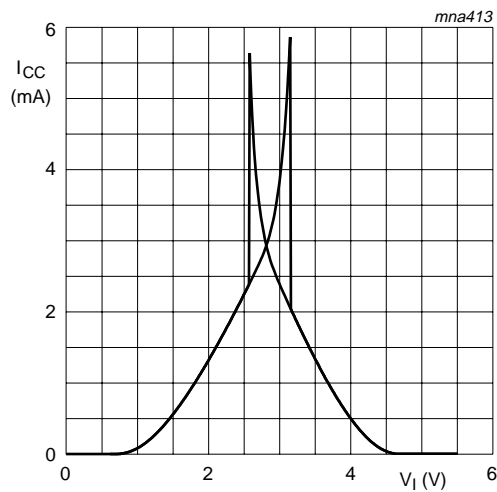




a. $V_{CC} = 3.0\text{ V}$



b. $V_{CC} = 4.5\text{ V}$



c. $V_{CC} = 5.5\text{ V}$

Fig 10. Typical 74AHC transfer characteristics

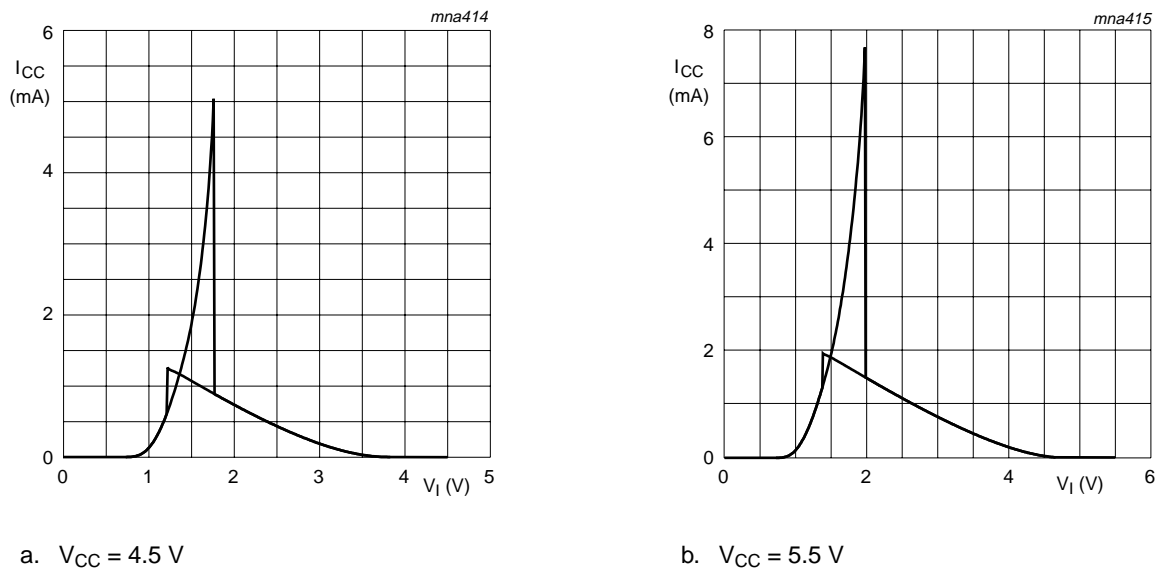
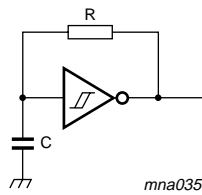


Fig 11. Typical 74AHCT transfer characteristics

14. Application information



For 74AHC14: $f = \frac{1}{T} \approx \frac{1}{0.55 \times RC}$

For 74AHCT14: $f = \frac{1}{T} \approx \frac{1}{0.60 \times RC}$

Fig 12. Relaxation oscillator

15. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

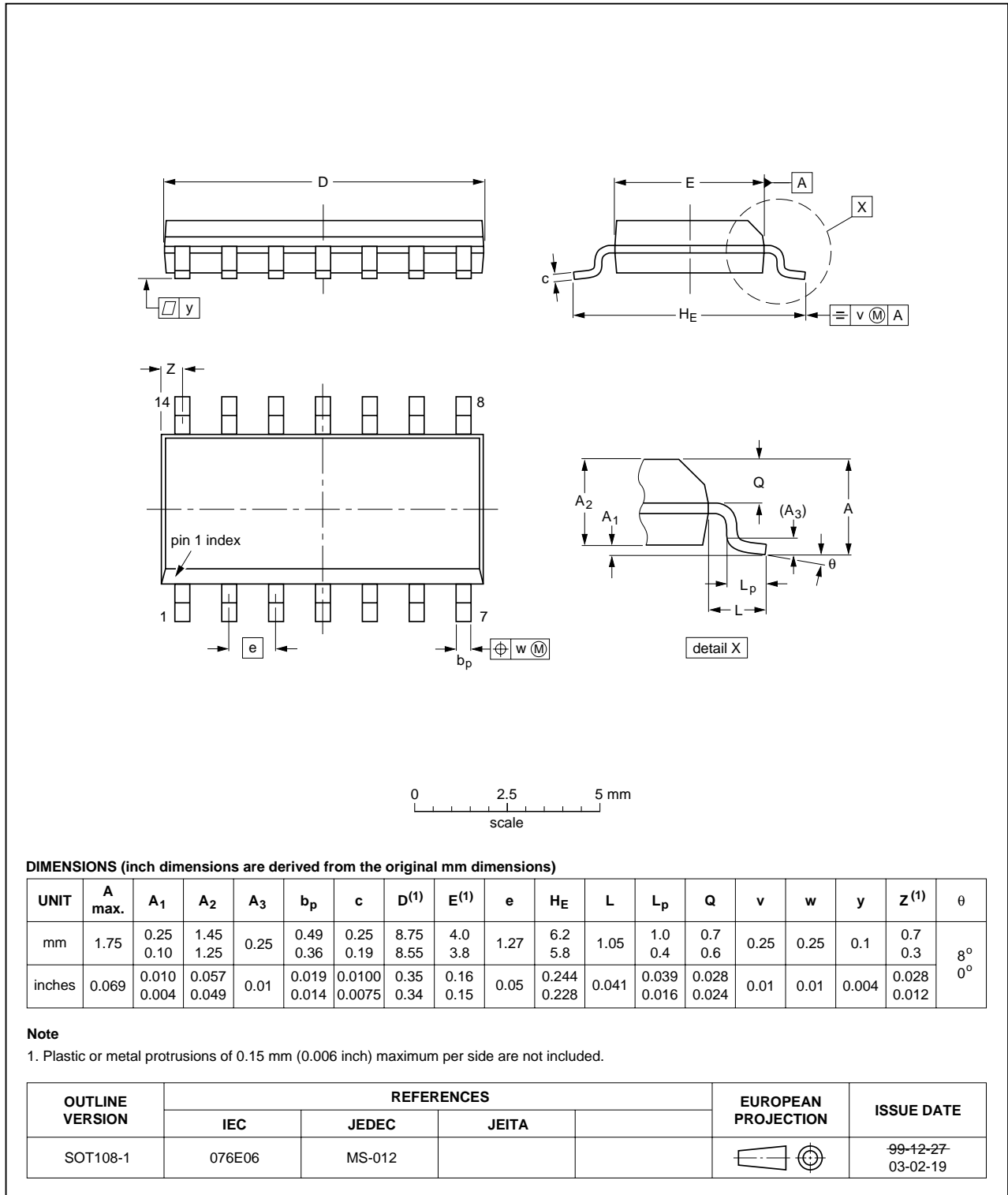


Fig 13. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

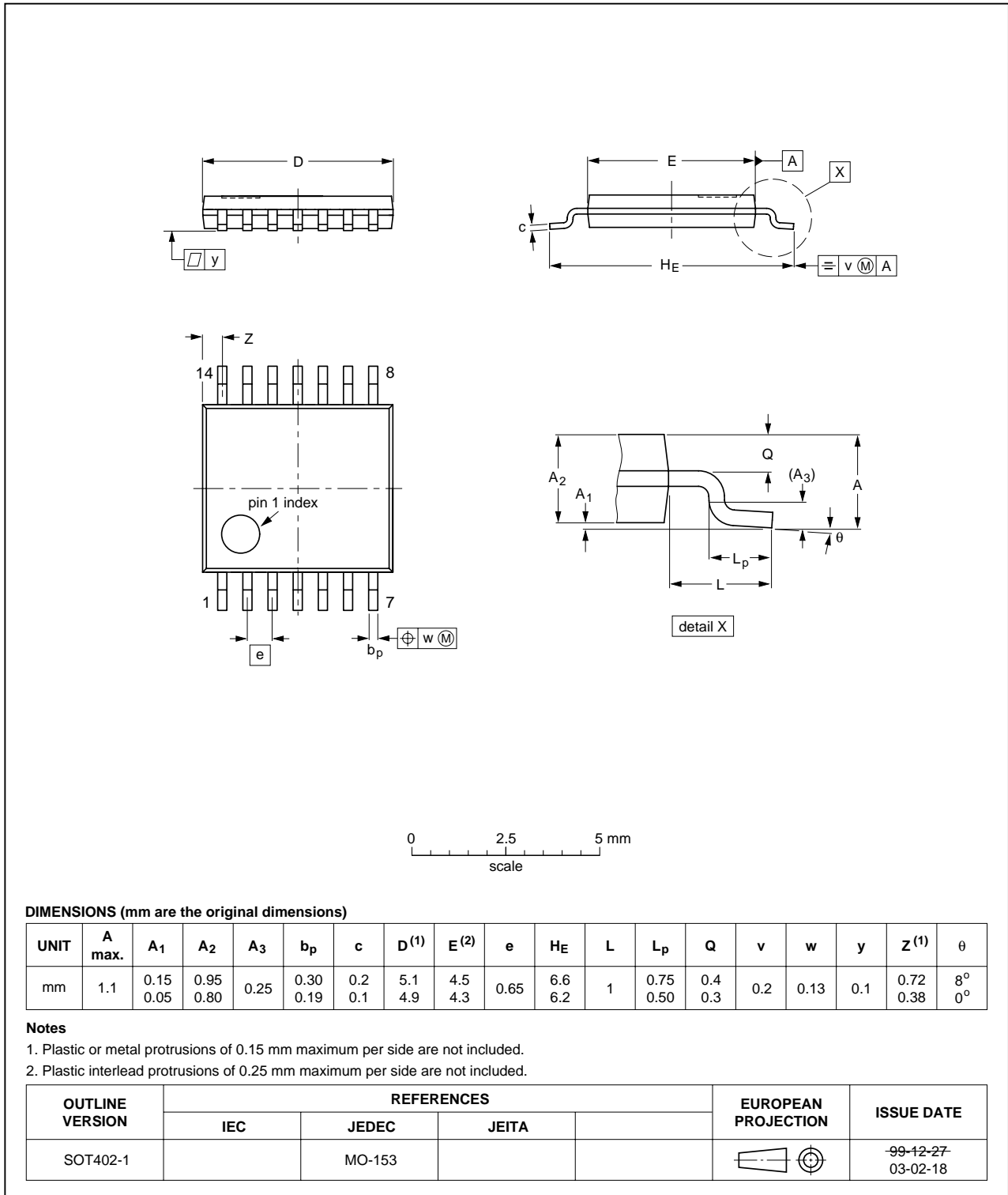


Fig 14. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

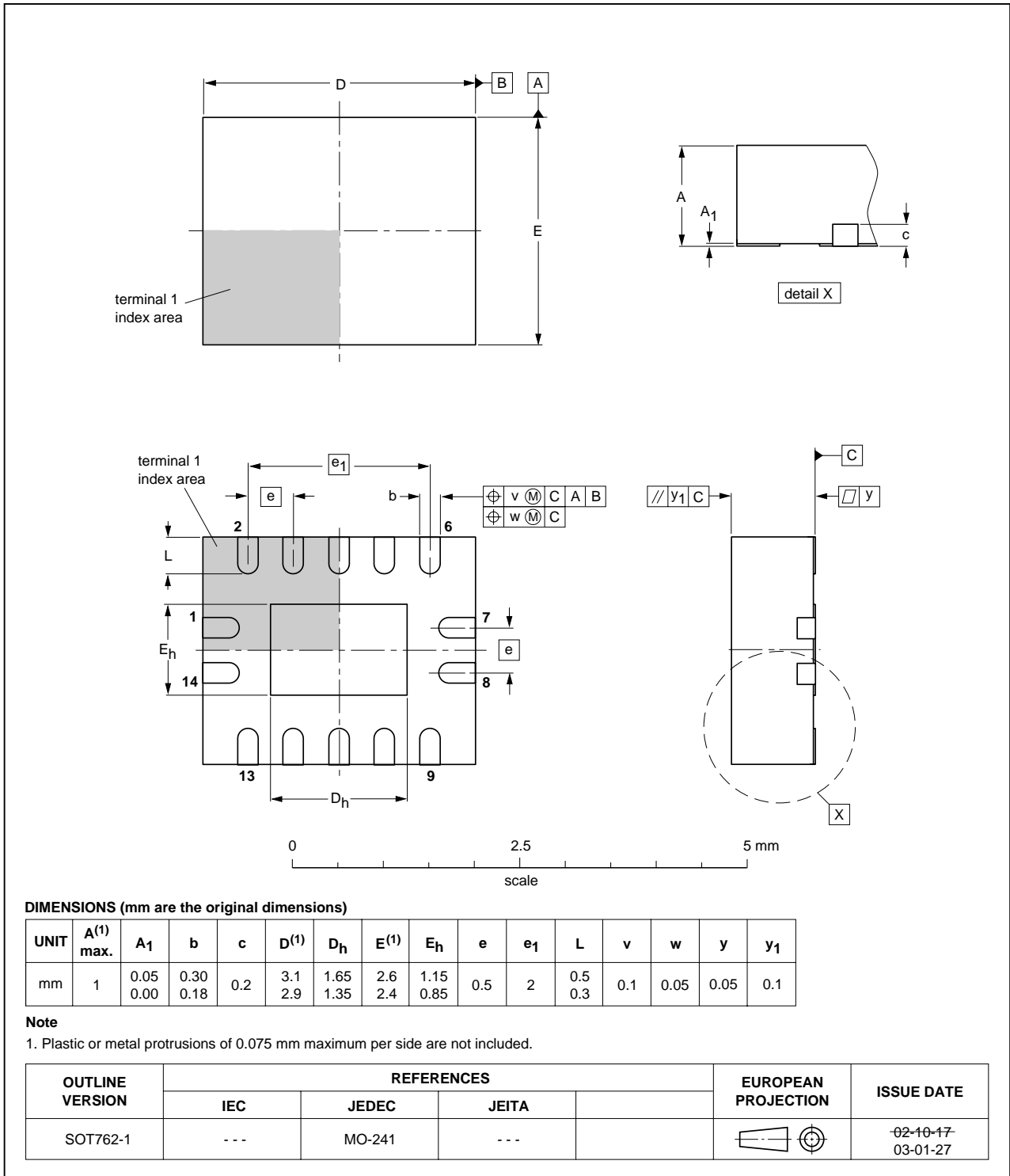


Fig 15. Package outline SOT762-1 (DHVQFN14)

16. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model

17. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT14_4	20080425	Product data sheet	-	74AHC_AHCT14_3
Modifications:		<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Table 6: the conditions for input leakage current have been changed. 		
74AHC_AHCT14_3	20030526	Product specification	-	74AHC_AHCT14_2
74AHC_AHCT14_2	19990927	Product specification	-	74AHC_AHCT14_N_1
74AHC_AHCT14_N_1	19990111	Preliminary specification	-	-

18. Legal information

18.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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20. Contents

1	General description	1
2	Features	1
3	Ordering information	2
4	Functional diagram	2
5	Pinning information	3
5.1	Pinning	3
5.2	Pin description	3
6	Functional description	4
7	Limiting values	4
8	Recommended operating conditions	4
9	Static characteristics	5
10	Dynamic characteristics	6
11	Waveforms	7
12	Transfer characteristics	8
13	Transfer characteristics waveforms	8
14	Application information	10
15	Package outline	11
16	Abbreviations	14
17	Revision history	14
18	Legal information	15
18.1	Data sheet status	15
18.2	Definitions	15
18.3	Disclaimers	15
18.4	Trademarks	15
19	Contact information	15
20	Contents	16

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